### imall

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### T-1 (3mm) SOLID STATE LAMP

Part Number: WP710A10LID High Efficiency Red

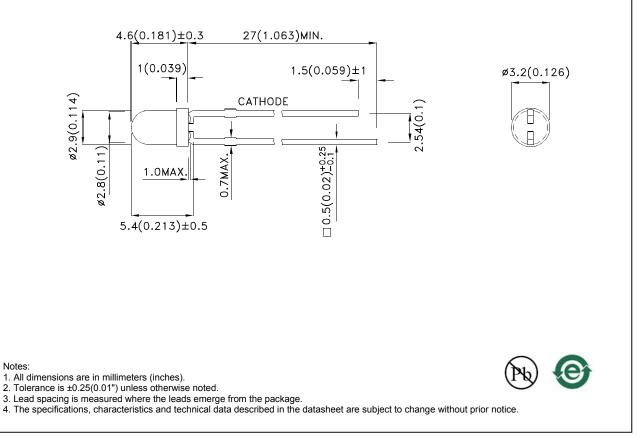
#### Features

- Low power consumption.
- Popular T-1 diameter package.
- General purpose leads.
- Reliable and rugged.
- Long life solid state reliability.
- Available on tape and reel.
- Low current IF=2mA operating.
- RoHS compliant.

#### Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

#### Package Dimensions



SPEC NO: DSAL0510 APPROVED: WYNEC REV NO: V.4A CHECKED: Allen Liu DATE: FEB/16/2013 DRAWN: Y.Liu PAGE: 1 OF 6 ERP: 1101029029

### Salaatian Cuida

Selection Guide					
Part No.	Dice	Lens Type	lv (mcd) [2] @ 2mA		Viewing Angle [1]
			Min.	Тур.	201/2
WP710A10LID	High Efficiency Red (GaAsP/GaP)	Red Diffused	0.35	1	40°
WFTIOATOLID	High Elliciency Red (GaAse/GaP)	Red Dillused	*0.2	*0.6	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.
\* Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

#### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627		nm	I⊧=2mA
λD [1]	Dominant Wavelength	High Efficiency Red	617		nm	I⊧=2mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45		nm	I⊧=2mA
С	Capacitance	High Efficiency Red	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red	1.7	2.5	V	I⊧=2mA
lr	Reverse Current	High Efficiency Red		10	uA	VR = 5V

Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V. 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

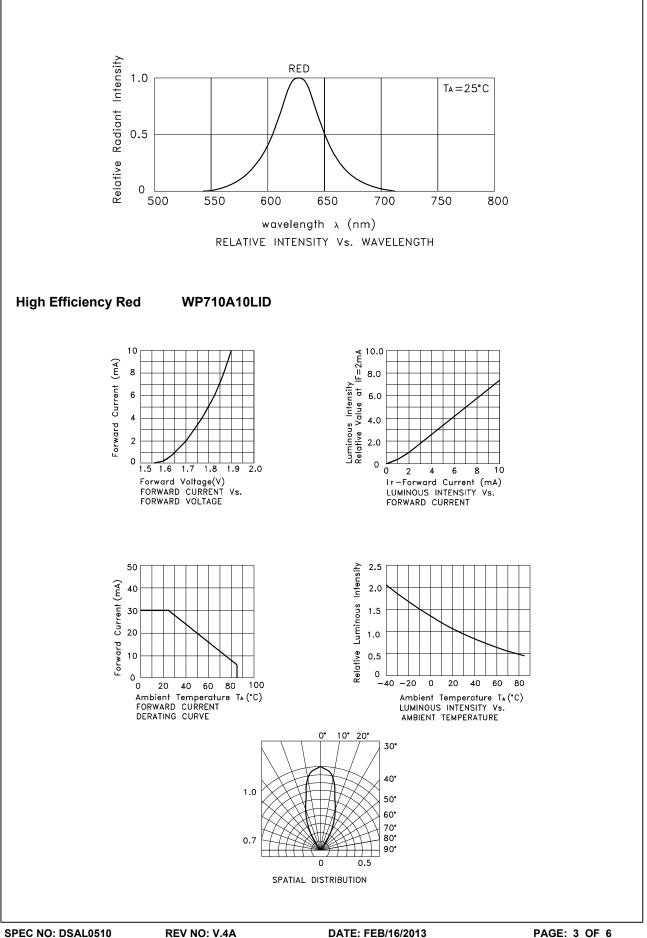
### Absolute Maximum Ratings at TA=25°C

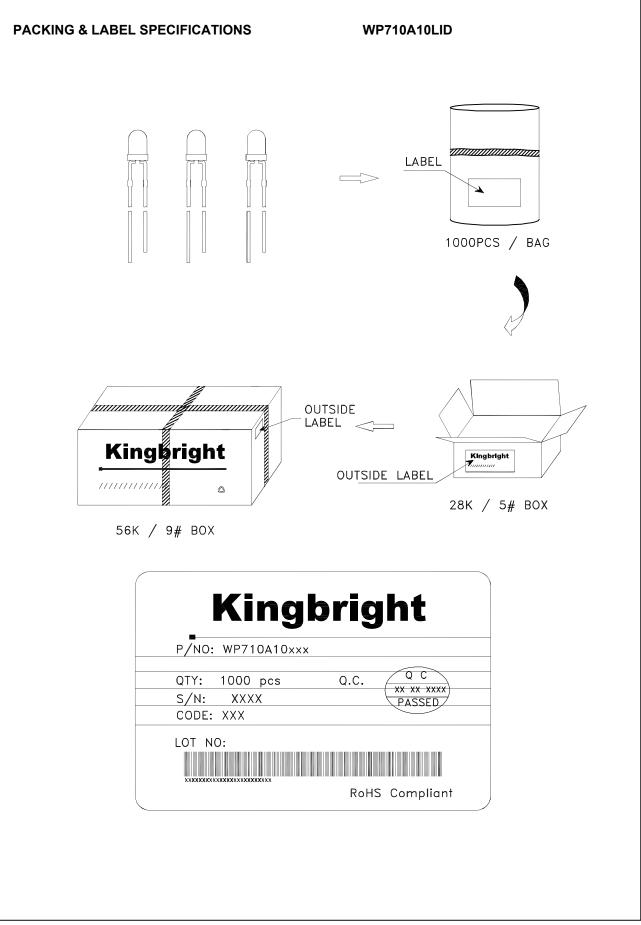
Parameter	High Efficiency Red	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	160	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [2]	260°C For 3 Seconds		
Lead Solder Temperature [3]	260°C For 5 Seconds		

Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
 2. 2mm below package base.

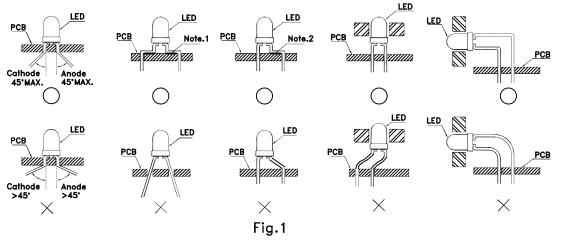
3. 5mm below package base.





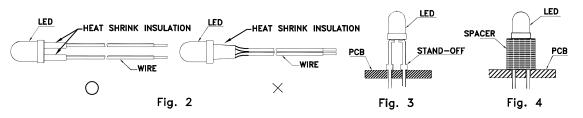
### PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)

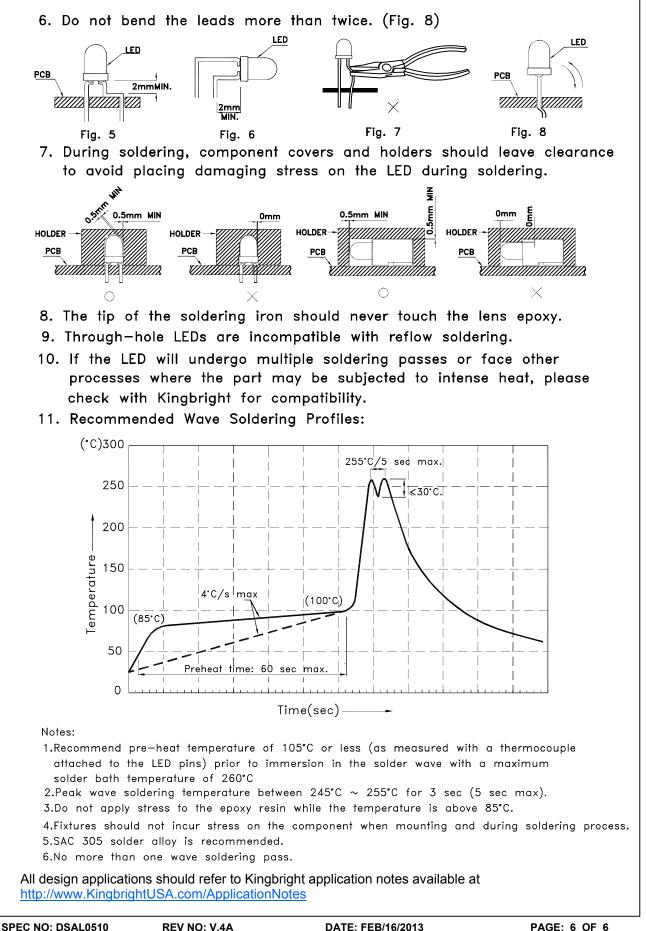


" $\bigcirc$  " Correct mounting method "imes" Incorrect mounting method

- 2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig.2)
- 3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



- 4. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
- 5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)



DATE: FEB/16/2013 DRAWN: Y.Liu